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背景

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- 2) 通訊作者投稿過程中，通過**機構郵箱**或**機構資訊**進行匹配
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- 5) Token使用申請將提交至機構管理員進行審核批復
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- 向 IEEE 完全 OA 期刊投稿的作者，將在步驟 1 中被要求接受 IEEE OA 條款和費用

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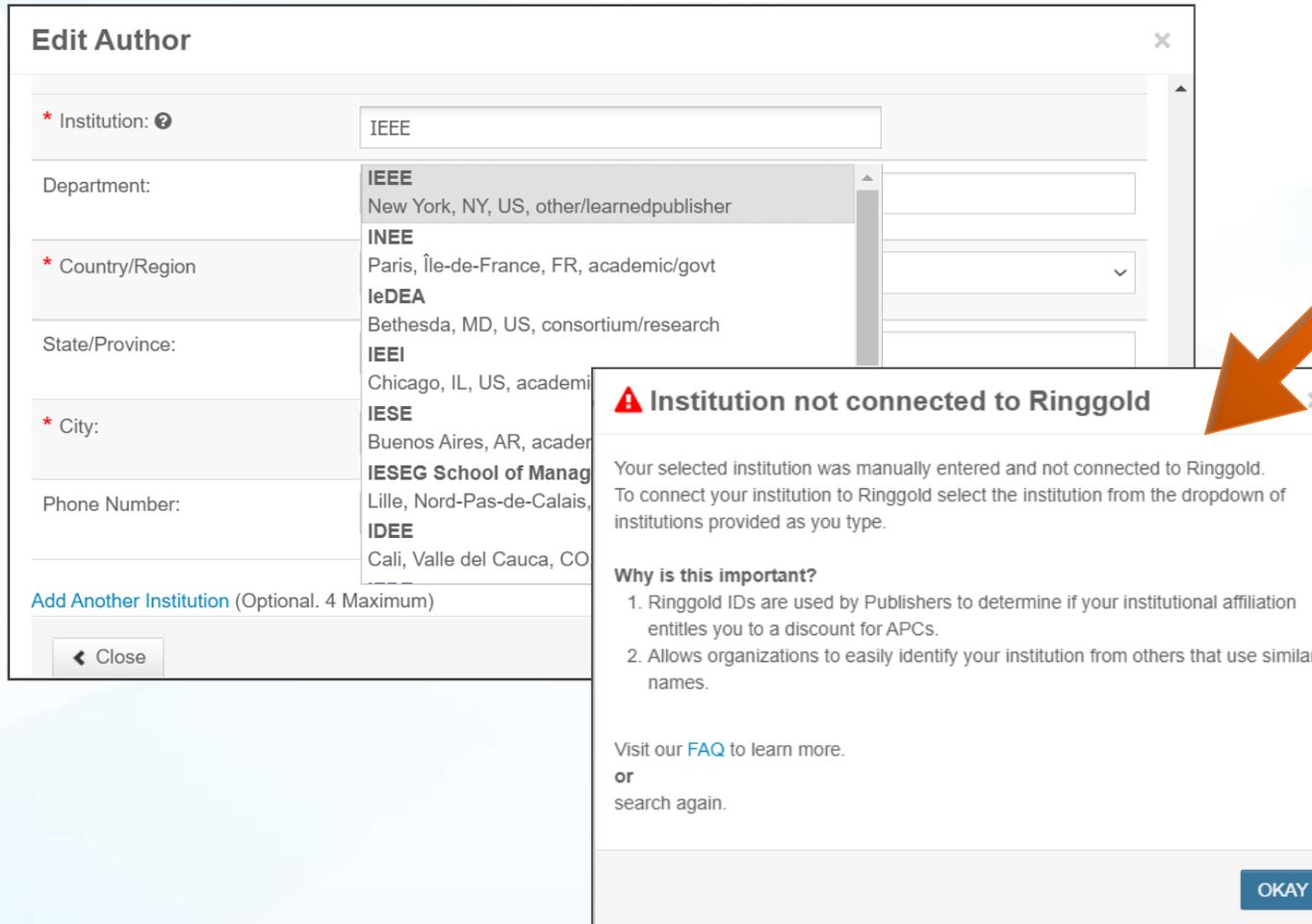
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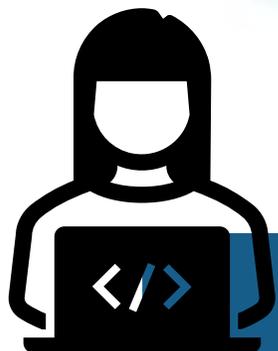
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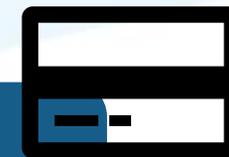
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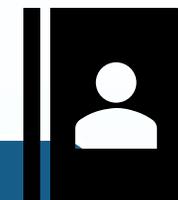
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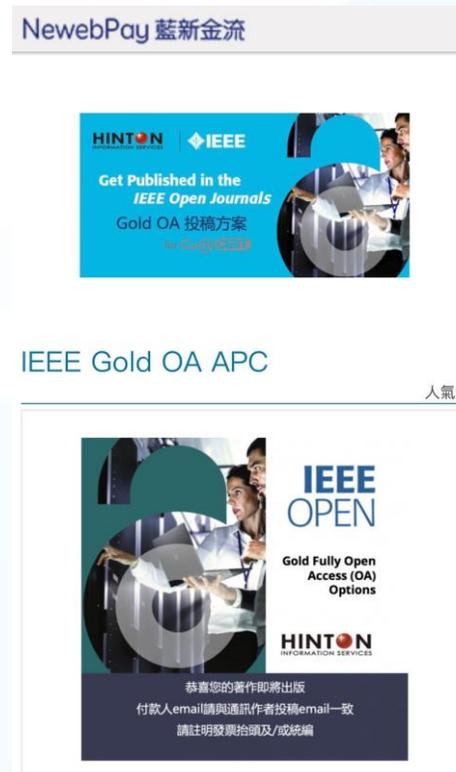
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